


## TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking		
Application Number :	10/050507		
Date :	2002-01-16		
First Named Applicant:	Lee Teck		
Confirmation Number:	7687		
Attorney Docket Number:	MTI-31607		
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I , the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>			
Submitted By:		Elec. Sign.	Sign. Capacity
Kristine M. Strodthoff Registered Number: 34259		/kms/	Attorney

Documents being submitted:	Files
us-ids	MTI-31607a-usidst.xml us-ids.dtd us-ids.xsl
Comments	